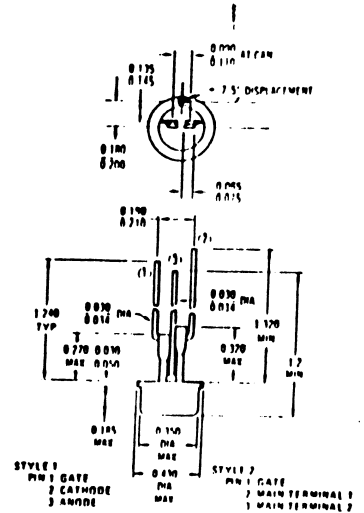


2N4186

SILICON
 CONTROLLED RECTIFIER

OUTLINE DRAWING



MAXIMUM RATINGS

(Apply over operating temperature range and for all case types unless otherwise noted)

Rating	Symbol	Value	Unit
*Peak Reverse Blocking Voltage (1)	V_{RRM}	200	Volts
Forward Current RMS	$I_T(RMS)$	80	Amp
*Peak Forward Surge Current (One cycle, 60 Hz, $T_J = -40$ to $+100^\circ C$)	I_{TSM}	100	Amp
Circuit Fusing Considerations ($T_J = -40$ to $+100^\circ C$; $t \leq 8.3$ ms)	I^2t	40	A^2s
*Peak Gate Power	P_{GM}	5.0	Watt
*Average Gate Power	$P_{G(AV)}$	0.5	Watt
*Peak Gate Current	I_{GM}	20	Amp
Peak Gate Voltage (2)	V_{GM}	10	Volts
*Operating Temperature Range	T_J	-40 to +100	$^\circ C$
*Storage Temperature Range	T_{stg}	-40 to +150	$^\circ C$

THERMAL CHARACTERISTICS

Characteristic	Symbol	Typ	Max	Unit
Thermal Resistance, Junction to Case	θ_{JC}	1.5	2.5*	$^\circ C/W$

(1) Ratings apply for zero or negative gate voltage. Devices should not be tested for blocking capability in a manner such that the voltage applied exceeds the rated blocking voltage.
 (2) Devices should not be operated with a positive bias applied to the gate concurrently with a negative potential applied to the anode.



ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
*Peak Forward Blocking Voltage (1) ($T_J = 100^\circ\text{C}$)	V_{DRM}	200	-	-	Volts
*Peak Forward Blocking Current (Rated V_{DRM} @ $T_J = 100^\circ\text{C}$, gate open)	I_{DRM}	-	-	2.0	mA
*Peak Reverse Blocking Current (Rated V_{DRM} @ $T_J = 100^\circ\text{C}$, gate open)	I_{RRM}	-	-	2.0	mA
Gate Trigger Current (Continuous dc) (2) (Anode Voltage = 7.0 Vdc, $R_L = 100 \Omega$) *(Anode Voltage = 7.0 Vdc, $R_L = 100 \Omega$, $T_C = -40^\circ\text{C}$)	I_{GT}	-	-	30 60	mA
Gate Trigger Voltage (Continuous dc) (Anode Voltage = 7.0 Vdc, $R_L = 100 \Omega$) *(Anode Voltage = 7.0 Vdc, $R_L = 100 \Omega$, $T_C = -40^\circ\text{C}$) *(Anode Voltage = 7.0 Vdc, $R_L = 100 \Omega$, $T_J = 100^\circ\text{C}$)	V_{GT}	-	-	1.5 2.5	Volts
*Forward "On" Voltage (pulsed, 1.0 ms max, duty cycle $\leq 1\%$) ($I_F = 15.7 \text{ A}$)	V_T	-	-	2.0	Volts
Holding Current (Anode Voltage = 7.0 Vdc, gate open) *(Anode Voltage = 7.0 Vdc, gate open, $T_C = -40^\circ\text{C}$)	I_H	-	-	30 60	mA
Turn-On Time ($t_d + t_r$) ($I_G = 20 \text{ mA dc}$, $I_F = 5.0 \text{ A dc}$)	t_{on}	-	1.0	-	μs
Turn-Off Time ($I_F = 5.0 \text{ A dc}$, $I_R = 5.0 \text{ A dc}$) ($I_F = 5.0 \text{ A dc}$, $I_R = 5.0 \text{ A dc}$, $T_J = 100^\circ\text{C}$) ($V_{FXM} = \text{rated voltage}$) ($dv/dt = 30 \text{ V}/\mu\text{s}$)	t_{off}	-	15 25	-	μs
Forward Voltage Application Rate (Gate open, $T_J = 100^\circ\text{C}$)	dv/dt	-	50	-	$\text{V}/\mu\text{s}$

- (1) Ratings apply for zero or negative gate voltage. These devices should not be tested with a constant current source for forward or reverse blocking capability such that the voltage applied exceeds the rated blocking voltage.
- (2) For optimum operation, i.e. faster turn on, lower switching losses, best dv/dt capability, recommended $I_{GT} = 200 \text{ mA}$ minimum.